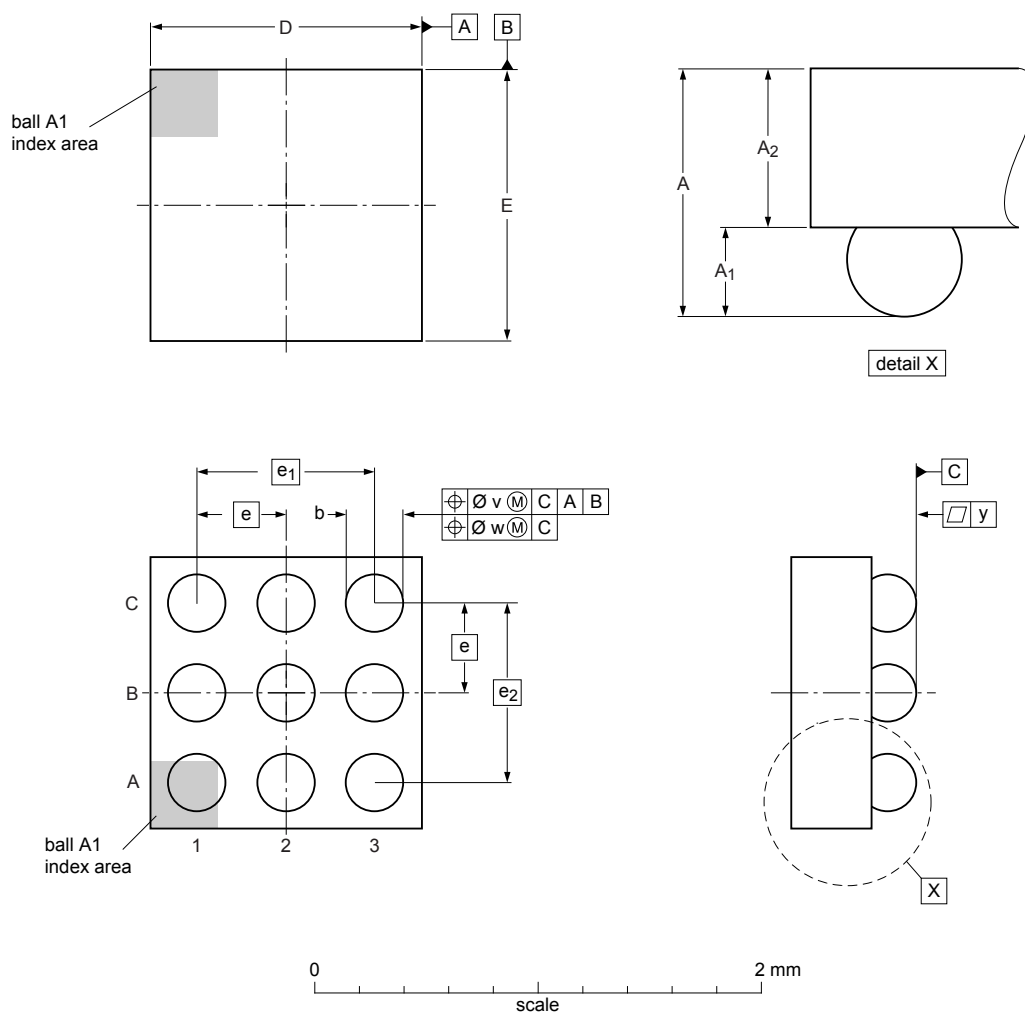


WLCSP9: wafer chip-scale package; 9 bumps; 1.22 x 1.22 x 0.5 mm

NCX8200UK



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y
max	0.54	0.23	0.325	0.29	1.25	1.25						
nom	0.50	0.20	0.300	0.26	1.22	1.22	0.4	0.8	0.8	0.05	0.015	0.03
min	0.46	0.17	0.275	0.23	1.19	1.19						

ncx8200uk_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
NCX8200UK						14-12-15 14-12-16